

RESINTECH SBG1 is a high capacity, shock resistant, gelular, Type 1, strongly basic anion exchange resin supplied in the chloride or hydroxide form as moist, tough, uniform, spherical beads. *RESINTECH SBG1* is intended for use in all types of deionization systems and chemical processing applications. It is similar to *RESINTECH SBG1P* but has a higher volumetric capacity and exhibits lower TOC leach rates. This makes it the better performer in single use applications such as in cartridge deionization and when high levels of regeneration are used such as in polishing mixed beds. On the other hand, *RESINTECH SBG1P* is more resistant to organic fouling and gives higher operating capacities at low regeneration levels such as those used in make up demineralizers.

FEATURES & BENEFITS

COMPLIES WITH FDA REGULATIONS FOR POTABLE WATER APPLICATIONS.

Conforms to paragraph 21CFR173.25 of the Food Additives Regulations of the F.D.A.*

HIGH TOTAL CAPACITY

Provides longer run lengths in single use applications or where high levels of regeneration are used such as in mixed bed polishers, cartridge demineralizers.

NSF/ANSI 61 CERTIFIED FOR MATERIAL SAFETY
 WQA Gold Seal Certified when ordered as SBG1-HP



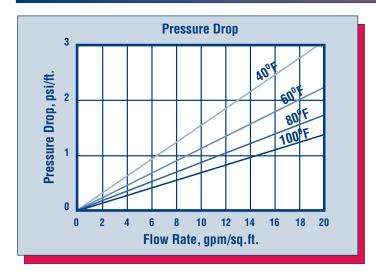
UNIFORM PARTICLE SIZE

16 to plus 50 mesh range; gives a LOWER PRESSURE DROP while maintaining SUPERIOR KINETICS.

- SUPERIOR PHYSICAL STABILITY
- LOWER TOC LEACH RATE

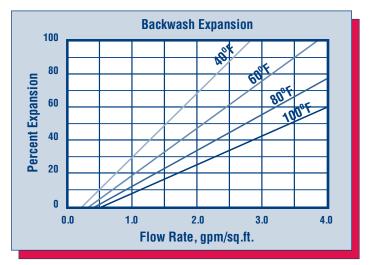
Makes it ideal for polishing mixed beds in wafer washing and other high purity water polishing applications.

HYDRAULIC PROPERTIES





The graph above shows the expected pressure loss per foot of bed depth as a function of flow rate, at various temperatures.



BACKWASH

After each cycle the resin bed should be backwashed at a rate that expands the bed 50 to 75 percent. This will remove any foreign matter and reclassify the bed. The graph above shows the expansion characteristics of *ResinTech SBG1* in the sodium form.

^{*} For potable water applications, the resin must be properly pre-treated, usually by multiple exhaustion and regeneration cycles, to ensure compliance with extractable levels

RESINTECH® SBG1

PHYSICAL PROPERTIES

Polymer Structure **Functional Group** Ionic Form, as shipped Physical Form Screen Size Distribution

+16 mesh (U.S. Std) -50 mesh (U.S. Std)

pH Range Sphericity

Uniformity Coefficient Water Retention Chloride Form

Hvdroxide Form

Solubility

Approximate Shipping Weight

CI Form OH Form Swelling CI- to OH-**Total Capacity** CI Form

OH Form

Styrene Crosslinked with DVB R-N-(CH₃)₃+Cl⁻ Chloride or Hydroxide Tough, Spherical Beads 16 to 50

< 5 percent < 1 percent 0 to 14 > 93 percent Approx. 1.6

43 to 50 percent Approx. 53 to 60 percent Insoluble

44 lbs/cu.ft. 41 lbs/cu.ft. 18 to 25 percent

1.45 meg/ml min 1.15 meg/ml min

SUGGESTED OPERATING CONDITIONS

Maximum Continuous Temperature

Hydroxide Form 140° F alt Form 170° F Minimum Bed Depth 24 inches

Backwash Rate 50 to 75 percent Bed Expansion Regenerant Concentration*

2 to 6 percent Regenerant Flow Rate 0.25 to 1.0 gpm/cu.ft. Regenerant Contact Time At least 40 Minutes Regenerant Level 4 to 10 pounds/cu.ft.

Displacement Rinse Rate Same as Regenerant Flow Rate

Displacement Rinse Volume 10 to 15 gals/cu.ft.

Fast Rinse Rate Same as Service Flow Rate 35 to 60 gals/cu.ft. Fast Rinse Volume

Service Flow Rates Polishing Mixed Beds 3 to 15 gpm/cu.ft. Non-Polishing Apps. 2 to 4 gpm/cu.ft.

OPERATING CAPACITY

The operating capacity of RESINTECH SBG1 for a variety of acids at various regeneration levels when treating an influent with a concentration 500 ppm, expressed as CaCO₃ is shown in the following table:

Pounds	Capacity Kilograms per cubic foot			
NaOH/ft ³	HCI	H ₂ SO ₄	H ₂ SiO ₃	H ₂ CO ₃
4	11.3	14.0	14.7	18.6
6	12.8	16.3	17.3	19.8
8	14.3	13.3	19.5	21.6
10	15.5	20.0	22.2	22.2

APPLICATIONS

DEMINERALIZATION –

RESINTECH SBG1 is highly recommended for use in mixed bed demineralizers, wherever complete ion removal; superior physical and osmotic stability and low TOC leachables are required such as in wafer fabrication and other ultrapure applications.

RESINTECH SBG1 has high total capacity and low swelling on regeneration and provides maximum operating capacity in cartridge deionization applications. It is ideal for single use applications such as precious metal recovery, radwaste disposal and purification of toxic waste streams.

Highly crosslinked Type 1, styrenic anion exchangers have greater thermal and oxidation resistance than other types of strong base resins. They can be operated and regenerated at higher temperatures. The combination of lower porosity, high total capacity and Type 1 functionality make RESINTECH SBG1 the resin of choice when water temperatures exceed 85°F and where the combination of carbon dioxide, borate and silica exceed 40% of the total anions.

RESINTECH SBG1P and RESINTECH SBG1 are quite similar; the difference between them is the degree of porosity. RESINTECH SBG1P has greater porosity that gives it faster kinetics, and greater ability to reversibly sorb slow moving ions such as Naturally occurring Organic Matter (NOM). At lower regeneration levels and where chlorides make up a substantial portion of the anion load, or where the removal and elution of naturally occurring organics is of concern RESINTECH SBG1P, SBACR or SBG2 should be considered. At the higher regeneration levels used in mixed bed polishers RESINTECH SBG1 provides higher capacity, and the lowest possible TOC leach rates.

*CAUTION:DO NOT MIX ION EXCHANGE RESIN WITH STRONG OXIDIZING AGENTS. Nitric acid and other strong oxidizing agents can cause explosive reactions when mixed with organic materials, such as ion exchange resins

Material Safety Data Sheets (MSDS) are available for all ResinTech Inc. products. To obtain a copy, contact your local ResinTech sales representative or our corporate headquarters.

They contain important health and safety information. That information may be needed to protect your employees and customers from any known health and safety hazards associated with our products. We recommend that you secure and study the pertinent MSDS for our products and any other products being used These suggestions and data are based on information we believe to be reliable. They are offered in good faith. However we do not make any guarantee or warranty. We caution against using these products in an unsafe manner or in violation of any patents; further we assume no liability for the consequences of any such actions.

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